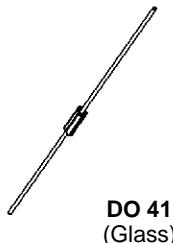


## SMALL SIGNAL SCHOTTKY DIODE



### DESCRIPTION

General purpose metal to silicon diode featuring very low turn-on voltage and fast switching.

This device has integrated protection against excessive voltage such as electrostatic discharges.

### ABSOLUTE RATINGS (limiting values)

| Symbol             | Parameter  |  | Value                      | Unit                                 |
|--------------------|--|--|----------------------------|--------------------------------------|
| $V_{RRM}$          | Repetitive Peak Reverse Voltage                                    |  | 80                         | V                                    |
| $I_F$              | Forward Continuous Current*  | $T_a = 70^\circ\text{C}$               | 500                        | mA                                   |
| $I_{FRM}$          | Repetitive Peak Forward Current*                                   | $t_p = 1\text{s}$<br>$\delta \leq 0.5$ | 3                          | A                                    |
| $I_{FSM}$          | Surge non Repetitive Forward Current*                              | $t_p \leq 10\text{ms}$                 | 10                         | A                                    |
| $T_{stg}$<br>$T_j$ | Storage and Junction Temperature Range                             |  | - 65 to 150<br>- 65 to 125 | $^\circ\text{C}$<br>$^\circ\text{C}$ |
| $T_L$              | Maximum Lead Temperature for Soldering during 10s at 4mm from Case |  | 230                        | $^\circ\text{C}$                     |

### THERMAL RESISTANCE

| Symbol        | Test Conditions   | Value | Unit               |
|---------------|-------------------|-------|--------------------|
| $R_{th(j-a)}$ | Junction-ambient* | 110   | $^\circ\text{C/W}$ |

### ELECTRICAL CHARACTERISTICS

#### STATIC CHARACTERISTICS

| Symbol   | Test Conditions          |                      | Min. | Typ. | Max. | Unit          |
|----------|--------------------------|----------------------|------|------|------|---------------|
| $I_R$ ** | $T_j = 25^\circ\text{C}$ | $V_R = 80\text{V}$   |      |      | 200  | $\mu\text{A}$ |
| $V_F$ ** | $T_j = 25^\circ\text{C}$ | $I_F = 10\text{mA}$  |      |      | 0.32 | V             |
|          | $T_j = 25^\circ\text{C}$ | $I_F = 100\text{mA}$ |      |      | 0.42 |               |
|          | $T_j = 25^\circ\text{C}$ | $I_F = 1\text{A}$    |      |      | 1    |               |

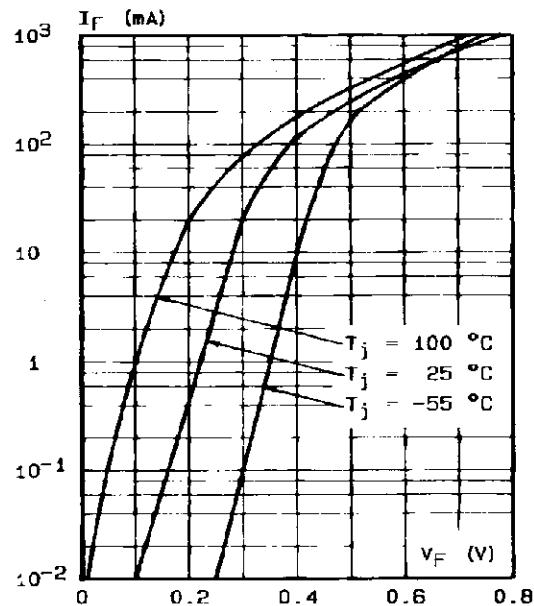
#### DYNAMIC CHARACTERISTICS

| Symbol | Test Conditions          |                   | Min.              | Typ. | Max. | Unit |
|--------|--------------------------|-------------------|-------------------|------|------|------|
| C      | $T_j = 25^\circ\text{C}$ | $f = 1\text{MHz}$ | $V_R = 0\text{V}$ | 120  |      | pF   |
|        |                          |                   | $V_R = 5\text{V}$ | 35   |      |      |

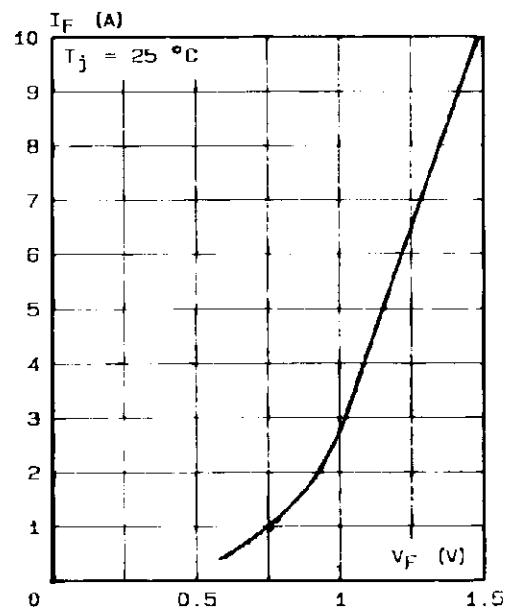
\* On infinite heatsink with 4mm lead length

\*\* Pulse test:  $t_p \leq 300\mu\text{s}$   $\delta < 2\%$ .

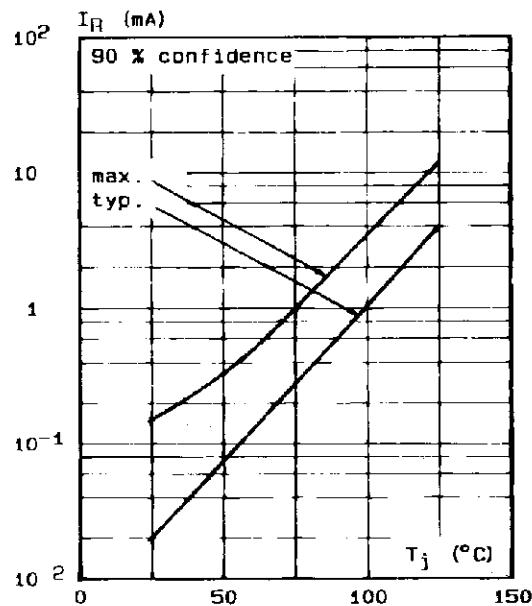
**Figure 1. Forward current versus forward voltage at low level (typical values).**



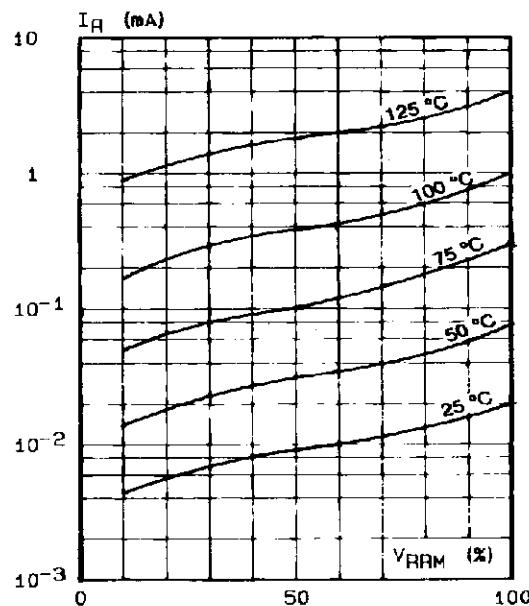
**Figure 2. Forward current versus forward voltage at high level (typical values).**



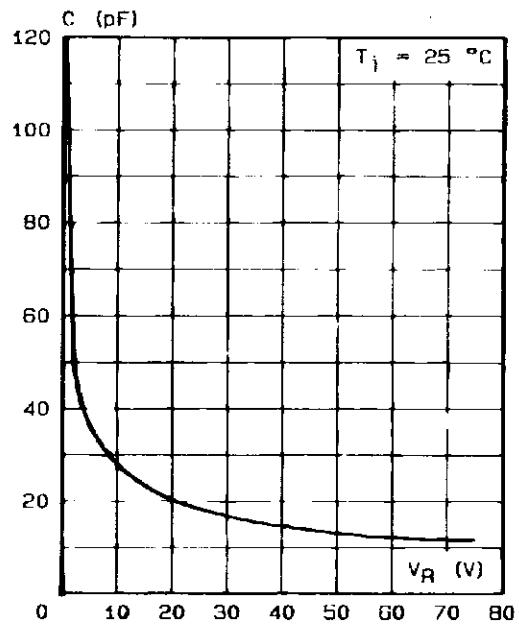
**Figure 3. Reverse current versus junction temperature.**



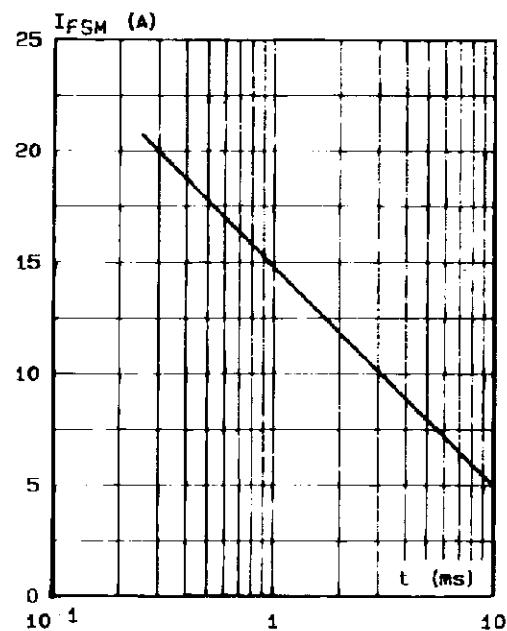
**Figure 4. Reverse current versus  $V_{RRM}$  in per cent.**



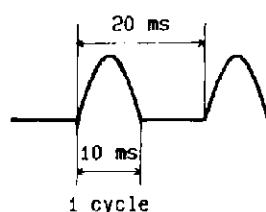
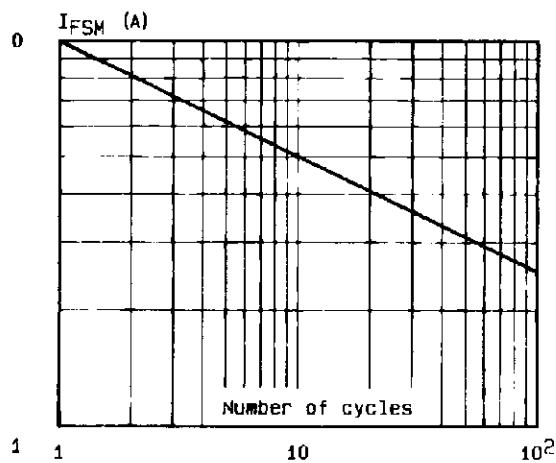
**Figure 5. Capacitance C versus reverse applied voltage  $V_R$  (typical values).**



**Figure 6. Surge non repetitive forward current for a rectangular pulse with  $t \leq 10$  ms.**



**Figure 7. Surge non repetitive forward current versus number of cycles.**



## BAT 49

### PACKAGE MECHANICAL DATA

DO 41 Glass

| REF.            | DIMENSIONS  |       |        |       | NOTES  |  |
|-----------------|-------------|-------|--------|-------|--|--|
|                 | Millimeters |       | Inches |       |  |  |
|                 | Min.        | Max.  | Min.   | Max.  |  |  |
| A               | 4.070       | 5.200 | 0.160  | 0.205 | 1 - The lead diameter $\varnothing$ D is not controlled over zone E  |  |
| B               | 28          |       | 1.102  |       | 2 - The minimum axial length within which the device may be placed with its leads bent at right angles is 0.59"(15 mm) |  |
| $\varnothing$ C | 2.040       | 2.710 | 0.080  | 0.107 |  |  |
| $\varnothing$ D | 0.712       | 0.863 | 0.028  | 0.034 |  |  |
| E               |             | 1.27  |        | 0.050 |  |  |

Cooling method : by convection and conduction

Marking: clear, ring at cathode end.

Weight: 0.34g

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